

MOSFET

600V CoolMOS™ P6 Power Transistor

CoolMOS™ is a revolutionary technology for high voltage power MOSFETs, designed according to the superjunction (SJ) principle and pioneered by Infineon Technologies. CoolMOS™ P6 series combines the experience of the leading SJ MOSFET supplier with high class innovation. The offered devices provide all benefits of a fast switching SJ MOSFET while not sacrificing ease of use. Extremely low switching and conduction losses make switching applications even more efficient, more compact, lighter and cooler.

Features

- Increased MOSFET dv/dt ruggedness
- Extremely low losses due to very low FOM $R_{DS(on)} \cdot Q_g$ and E_{oss}
- Very high commutation ruggedness
- Easy to use/drive
- Pb-free plating, Halogen free mold compound

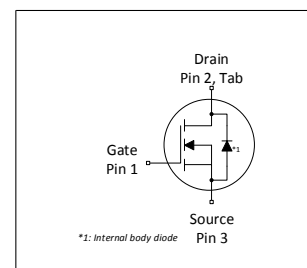
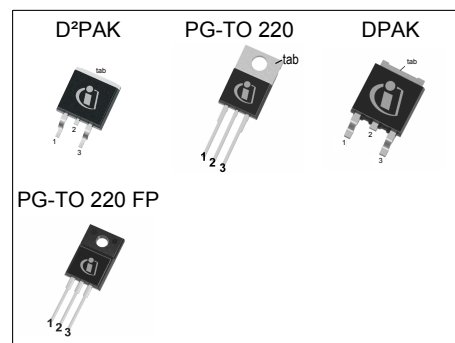
Potential applications

PFC stages, hard switching PWM stages and resonant switching stages for e.g. PC Silverbox, Adapter, LCD & PDP TV, Lighting, Server, Telecom and UPS.

Product validation

Fully qualified according to JEDEC for Industrial Applications

Please note: For MOSFET paralleling the use of ferrite beads on the gate or separate totem poles is generally recommended.



RoHS

Table 1 Key Performance Parameters

Parameter	Value	Unit
$V_{DS} @ T_{j,max}$	650	V
$R_{DS(on),max}$	380	mΩ
$Q_{g,typ}$	19	nC
$I_{D,pulse}$	29	A
$E_{oss}@400V$	2.7	μJ
Body diode di/dt	500	A/μs

Type / Ordering Code	Package	Marking	Related Links
IPB60R380P6	PG-TO263-3	6R380P6	see Appendix A
IPP60R380P6	PG-TO220-3		
IPD60R380P6	PG-TO252-3		
IPA60R380P6	PG-TO220 FullPAK		

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1 Maximum ratings

at $T_j = 25^\circ\text{C}$, unless otherwise specified

Table 2 Maximum ratings

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Continuous drain current ¹⁾	I_D	-	-	10.6 6.7	A	$T_C=25^\circ\text{C}$ $T_C=100^\circ\text{C}$
Pulsed drain current ²⁾	$I_{D,pulse}$	-	-	29	A	$T_C=25^\circ\text{C}$
Avalanche energy, single pulse	E_{AS}	-	-	210	mJ	$I_D=1.8\text{A}$; $V_{DD}=50\text{V}$; see table 10
Avalanche energy, repetitive	E_{AR}	-	-	0.32	mJ	$I_D=1.8\text{A}$; $V_{DD}=50\text{V}$; see table 10
Avalanche current, repetitive	I_{AR}	-	-	1.8	A	-
MOSFET dv/dt ruggedness	dv/dt	-	-	100	V/ns	$V_{DS}=0\dots400\text{V}$
Gate source voltage (static)	V_{GS}	-20	-	20	V	static;
Gate source voltage (dynamic)	V_{GS}	-30	-	30	V	AC ($f>1\text{ Hz}$)
Power dissipation (Non FullPAK) TO-220, TO-247	P_{tot}	-	-	83	W	$T_C=25^\circ\text{C}$
Power dissipation (FullPAK) TO-220FP	P_{tot}	-	-	31	W	$T_C=25^\circ\text{C}$
Storage temperature	T_{stg}	-55	-	150	$^\circ\text{C}$	-
Operating junction temperature	T_j	-55	-	150	$^\circ\text{C}$	-
Mounting torque (Non FullPAK) TO-220, TO-247	-	-	-	60	Ncm	M3 and M3.5 screws
Mounting torque (FullPAK) TO-220FP	-	-	-	50	Ncm	M2.5 screws
Continuous diode forward current	I_S	-	-	9.2	A	$T_C=25^\circ\text{C}$
Diode pulse current ²⁾	$I_{S,pulse}$	-	-	29	A	$T_C=25^\circ\text{C}$
Reverse diode dv/dt ³⁾	dv/dt	-	-	15	V/ns	$V_{DS}=0\dots400\text{V}$, $I_{SD}\leq I_S$, $T_j=25^\circ\text{C}$ see table 8
Maximum diode commutation speed	di/dt	-	-	500	A/ μs	$V_{DS}=0\dots400\text{V}$, $I_{SD}\leq I_S$, $T_j=25^\circ\text{C}$ see table 8
Insulation withstand voltage for TO-220FP	V_{ISO}	-	-	2500	V	V_{rms} , $T_C=25^\circ\text{C}$, $t=1\text{min}$

¹⁾ Limited by $T_{j,max}$. Maximum duty cycle $D=0.75$

²⁾ Pulse width t_p limited by $T_{j,max}$

³⁾ Identical low side and high side switch with identical R_G

2 Thermal characteristics

Table 3 Thermal characteristics (Non FullPAK) TO-220, TO-247

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	R_{thJC}	-	-	1.5	°C/W	-
Thermal resistance, junction - ambient	R_{thJA}	-	-	62	°C/W	lead
Soldering temperature, wavesoldering only allowed at leads	T_{sold}	-	-	260	°C	1.6mm (0.063 in.) from case for 10s

Table 4 Thermal characteristics (FullPAK) TO-220FP

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	R_{thJC}	-	-	4	°C/W	-
Thermal resistance, junction - ambient	R_{thJA}	-	-	80	°C/W	lead
Soldering temperature, wavesoldering only allowed at leads	T_{sold}	-	-	260	°C	1.6mm (0.063 in.) from case for 10s

Table 5 Thermal characteristics TO-252

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	R_{thJC}	-	-	1.5	°C/W	-
Thermal resistance, junction - ambient	R_{thJA}	-	-	62	°C/W	device on PCB, minimal footprint
Thermal resistance, junction - ambient for SMD version	R_{thJA}	-	35	45	°C/W	Device on 40mm*40mm*1.5mm epoxy PCB FR4 with 6cm ² (one layer, 70µm thickness) copper area for drain connection and cooling. PCB is vertical without air stream cooling.
Soldering temperature, wave & reflow soldering allowed	T_{sold}	-	-	260	°C	reflow MSL1

3 Electrical characteristics

at $T_j=25^\circ\text{C}$, unless otherwise specified

Table 6 Static characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(BR)DSS}$	600	-	-	V	$V_{GS}=0V$, $I_D=1mA$
Gate threshold voltage	$V_{(GS)th}$	3.5	4.0	4.5	V	$V_{DS}=V_{GS}$, $I_D=0.32mA$
Zero gate voltage drain current	I_{DSS}	-	-	1	μA	$V_{DS}=600$, $V_{GS}=0V$, $T_j=25^\circ\text{C}$ $V_{DS}=600$, $V_{GS}=0V$, $T_j=150^\circ\text{C}$
Gate-source leakage current	I_{GSS}	-	-	100	nA	$V_{GS}=20V$, $V_{DS}=0V$
Drain-source on-state resistance	$R_{DS(on)}$	-	0.342 0.889	0.380 -	Ω	$V_{GS}=10V$, $I_D=3.8A$, $T_j=25^\circ\text{C}$ $V_{GS}=10V$, $I_D=3.8A$, $T_j=150^\circ\text{C}$
Gate resistance	R_G	-	7.8	-	Ω	$f=1MHz$, open drain

Table 7 Dynamic characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input capacitance	C_{iss}	-	877	-	pF	$V_{GS}=0V$, $V_{DS}=100V$, $f=1MHz$
Output capacitance	C_{oss}	-	42	-	pF	$V_{GS}=0V$, $V_{DS}=100V$, $f=1MHz$
Effective output capacitance, energy related ¹⁾	$C_{o(er)}$	-	33	-	pF	$V_{GS}=0V$, $V_{DS}=0...400V$
Effective output capacitance, time related ²⁾	$C_{o(tr)}$	-	135	-	pF	$I_D=\text{constant}$, $V_{GS}=0V$, $V_{DS}=0...400V$
Turn-on delay time	$t_{d(on)}$	-	12	-	ns	$V_{DD}=400V$, $V_{GS}=13V$, $I_D=4.8A$, $R_G=3.4\Omega$; see table 9
Rise time	t_r	-	6	-	ns	$V_{DD}=400V$, $V_{GS}=13V$, $I_D=4.8A$, $R_G=3.4\Omega$; see table 9
Turn-off delay time	$t_{d(off)}$	-	33	-	ns	$V_{DD}=400V$, $V_{GS}=13V$, $I_D=4.8A$, $R_G=3.4\Omega$; see table 9
Fall time	t_f	-	7	-	ns	$V_{DD}=400V$, $V_{GS}=13V$, $I_D=4.8A$, $R_G=3.4\Omega$; see table 9

Table 8 Gate charge characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Gate to source charge	Q_{gs}	-	5.4	-	nC	$V_{DD}=400V$, $I_D=4.8A$, $V_{GS}=0$ to $10V$
Gate to drain charge	Q_{gd}	-	7	-	nC	$V_{DD}=400V$, $I_D=4.8A$, $V_{GS}=0$ to $10V$
Gate charge total	Q_g	-	19	-	nC	$V_{DD}=400V$, $I_D=4.8A$, $V_{GS}=0$ to $10V$
Gate plateau voltage	$V_{plateau}$	-	6.1	-	V	$V_{DD}=400V$, $I_D=4.8A$, $V_{GS}=0$ to $10V$

¹⁾ $C_{o(er)}$ is a fixed capacitance that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 400V

²⁾ $C_{o(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 400V

Table 9 Reverse diode characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Diode forward voltage	V_{SD}	-	0.9	-	V	$V_{GS}=0V$, $I_F=4.8A$, $T_J=25^{\circ}C$
Reverse recovery time	t_{rr}	-	232	-	ns	$V_R=400V$, $I_F=4.8A$, $di_F/dt=100A/\mu s$; see table 8
Reverse recovery charge	Q_{rr}	-	2.1	-	μC	$V_R=400V$, $I_F=4.8A$, $di_F/dt=100A/\mu s$; see table 8
Peak reverse recovery current	I_{rrm}	-	17	-	A	$V_R=400V$, $I_F=4.8A$, $di_F/dt=100A/\mu s$; see table 8

4 Electrical characteristics diagrams

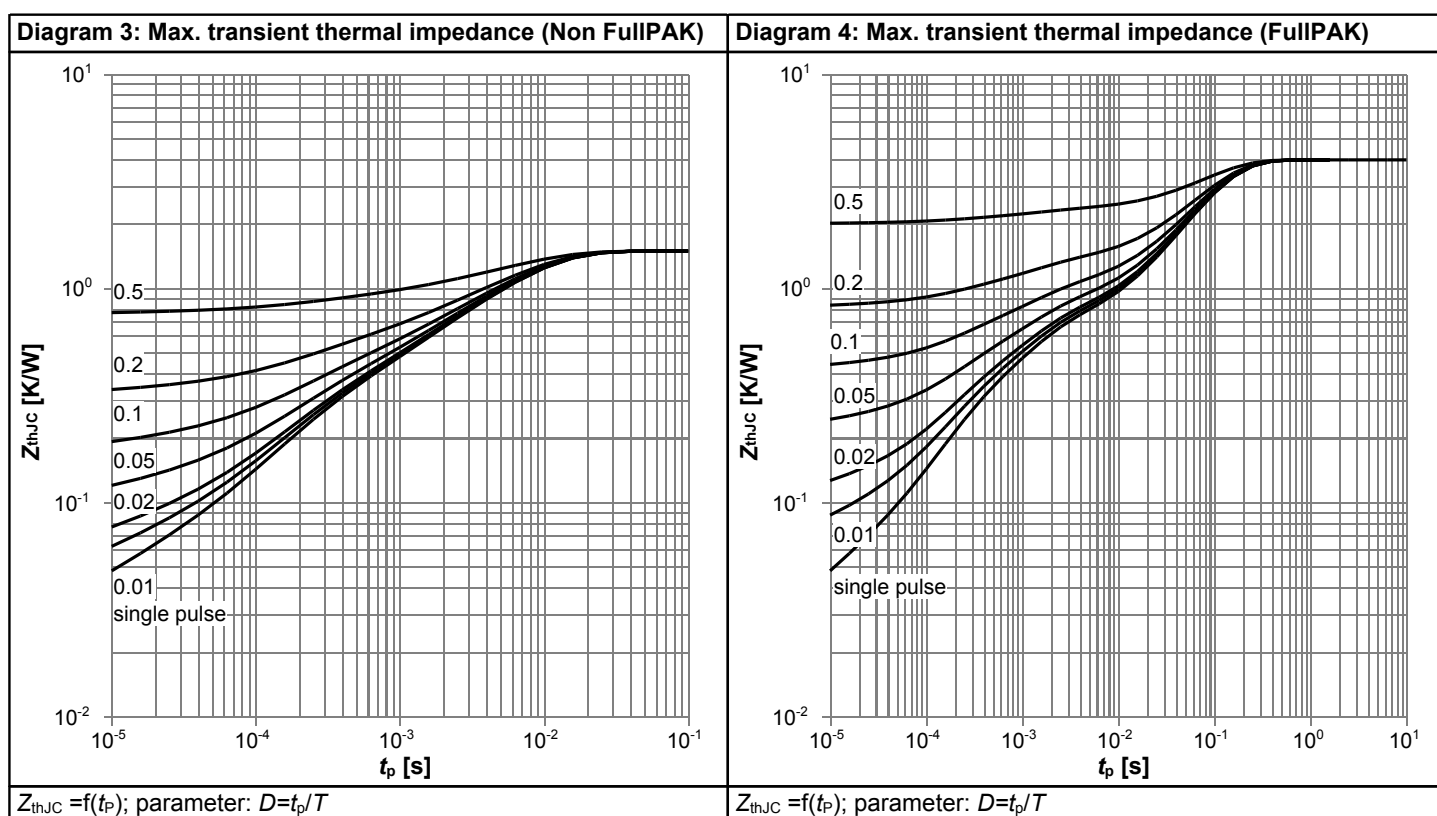
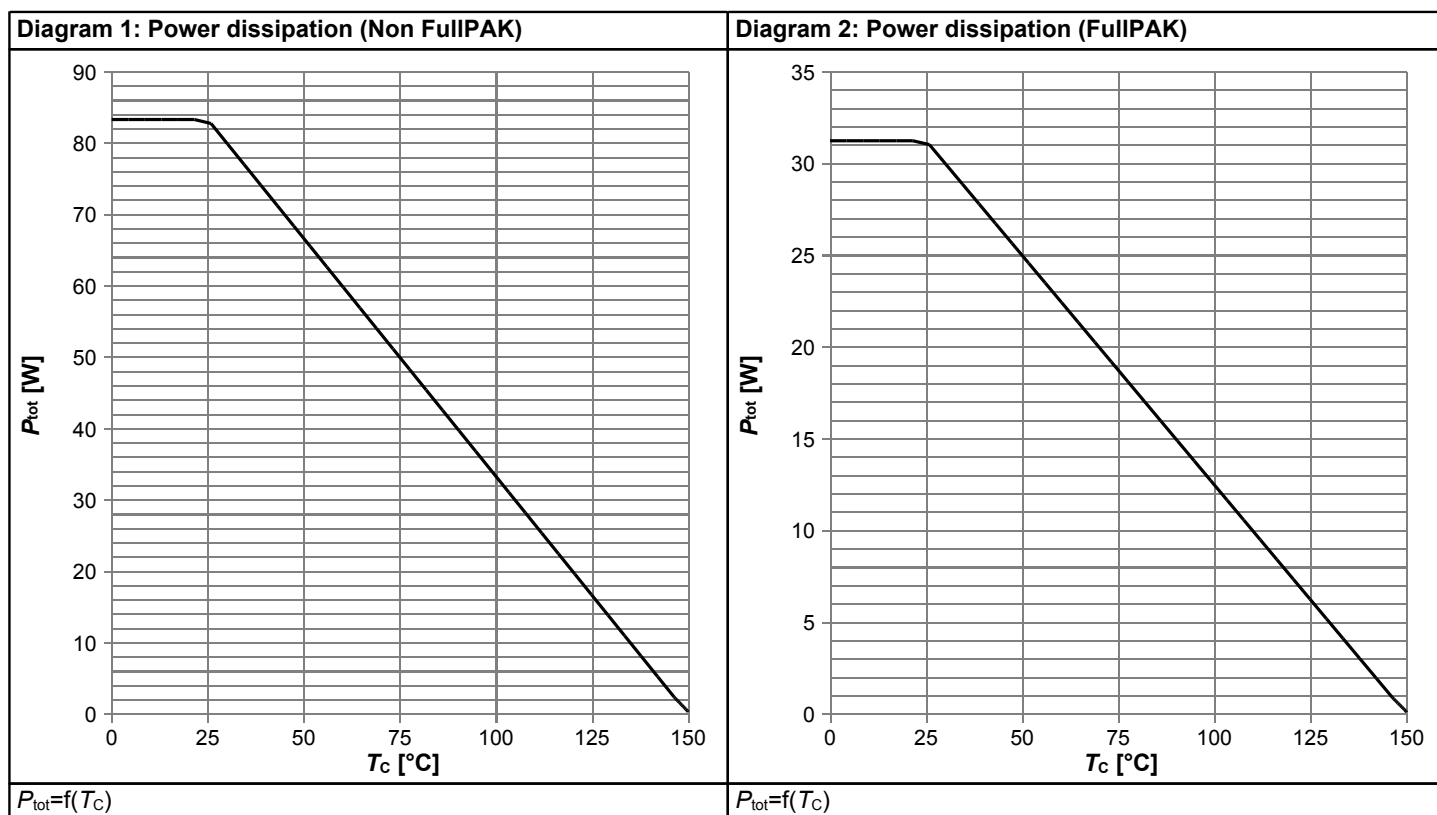
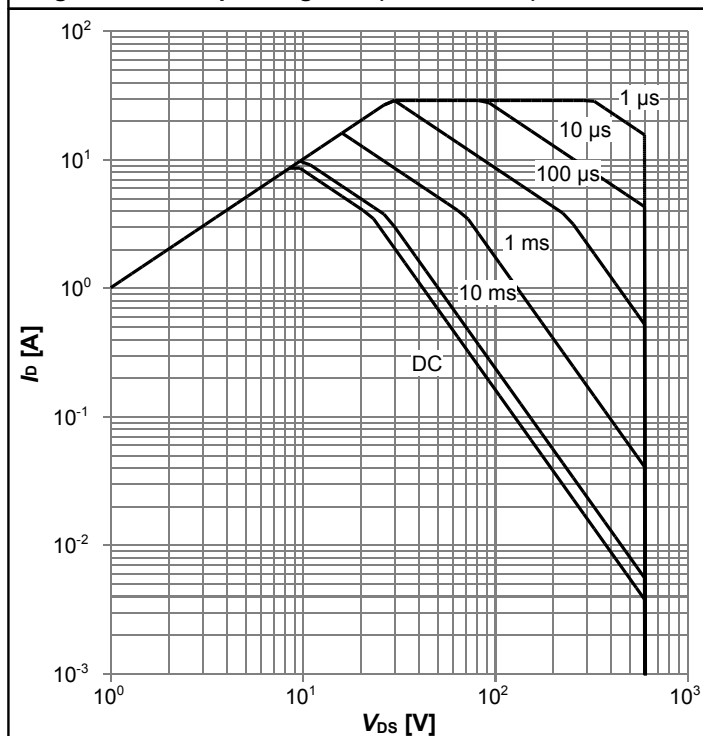
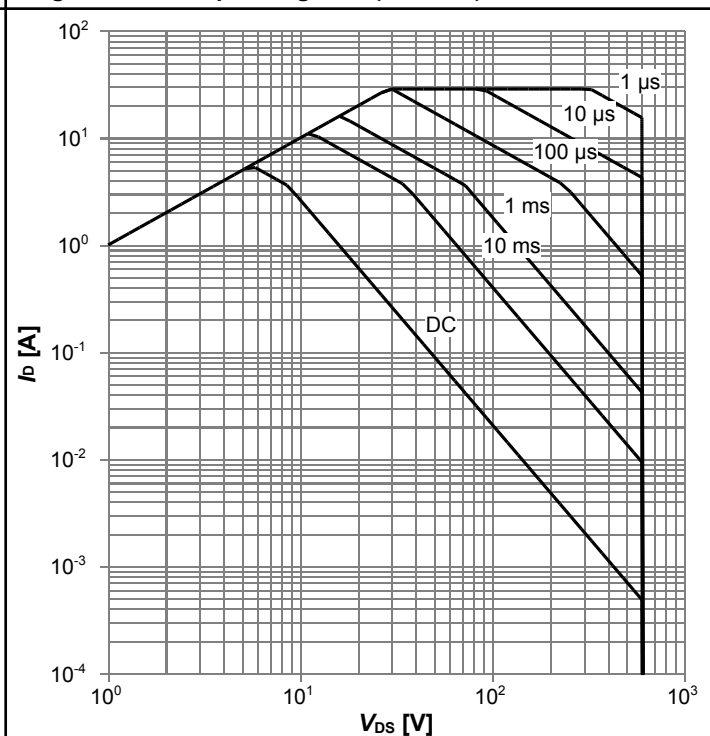


Diagram 5: Safe operating area (Non FullPAK)



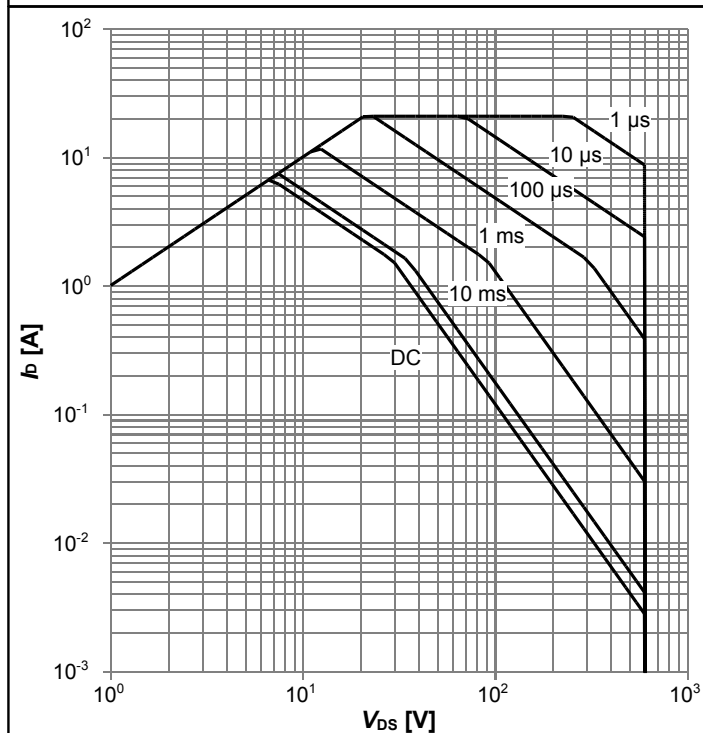
$I_D=f(V_{DS})$; $T_C=25\text{ °C}$; $D=0$; parameter: t_p

Diagram 6: Safe operating area (FullPAK)



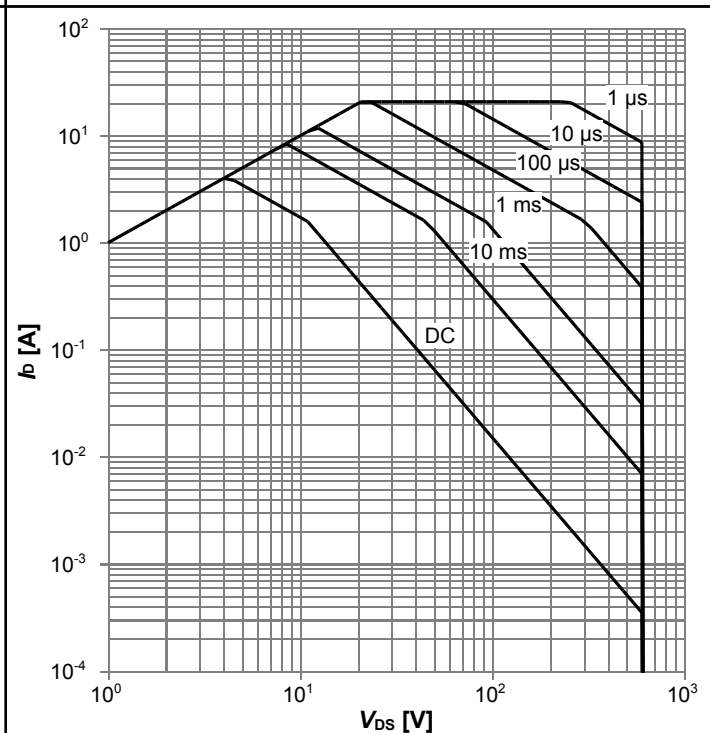
$I_D=f(V_{DS})$; $T_C=25\text{ °C}$; $D=0$; parameter: t_p

Diagram 7: Safe operating area (Non FullPAK)



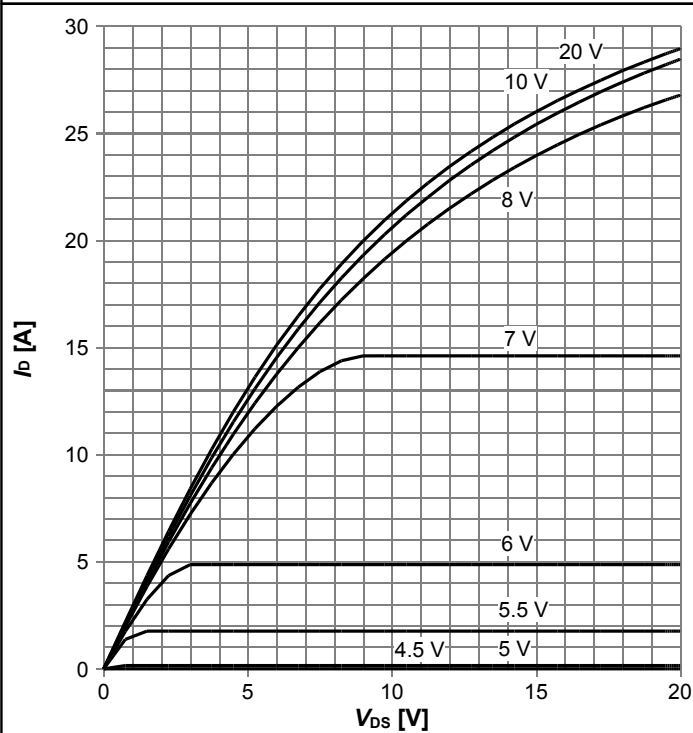
$I_D=f(V_{DS})$; $T_C=80\text{ °C}$; $D=0$; parameter: t_p

Diagram 8: Safe operating area (FullPAK)



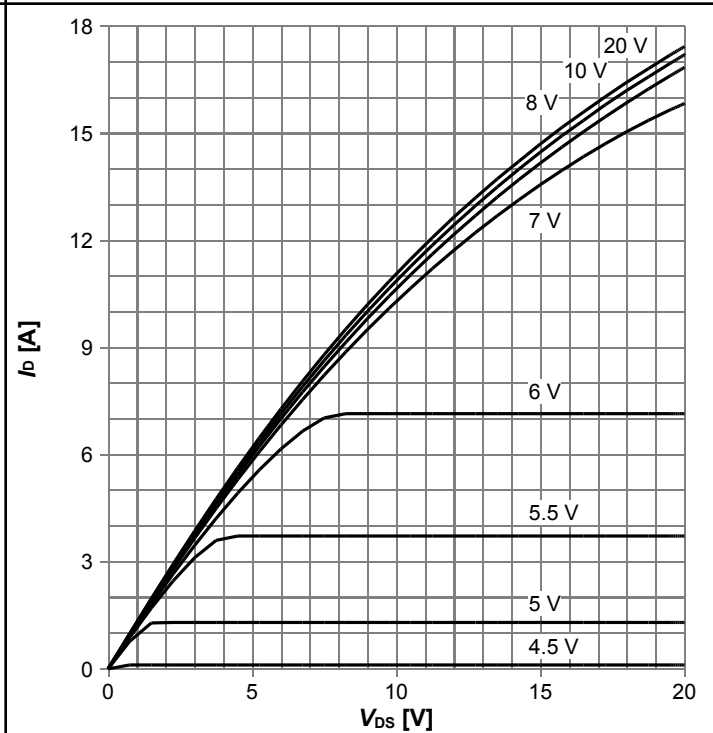
$I_D=f(V_{DS})$; $T_C=80\text{ °C}$; $D=0$; parameter: t_p

Diagram 9: Typ. output characteristics



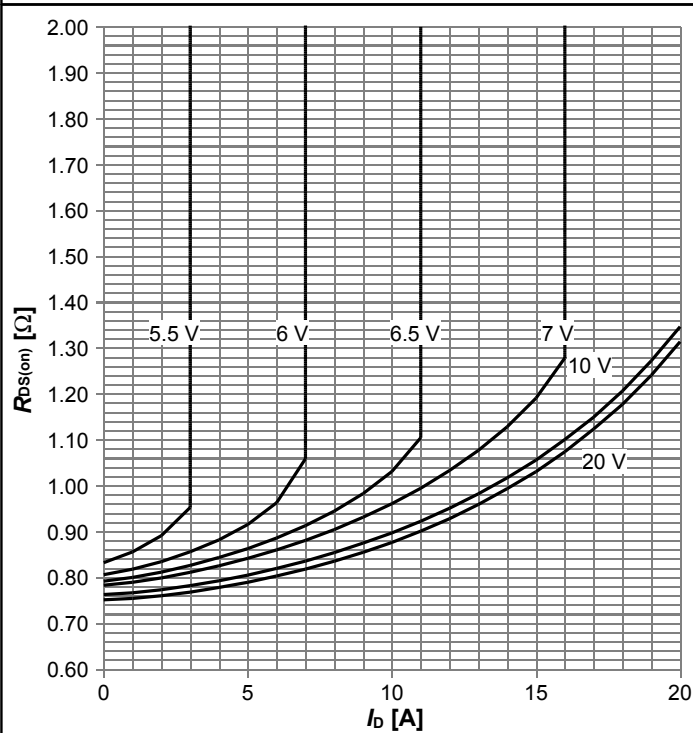
$I_D = f(V_{DS})$; $T_j = 25\text{ °C}$; parameter: V_{GS}

Diagram 10: Typ. output characteristics



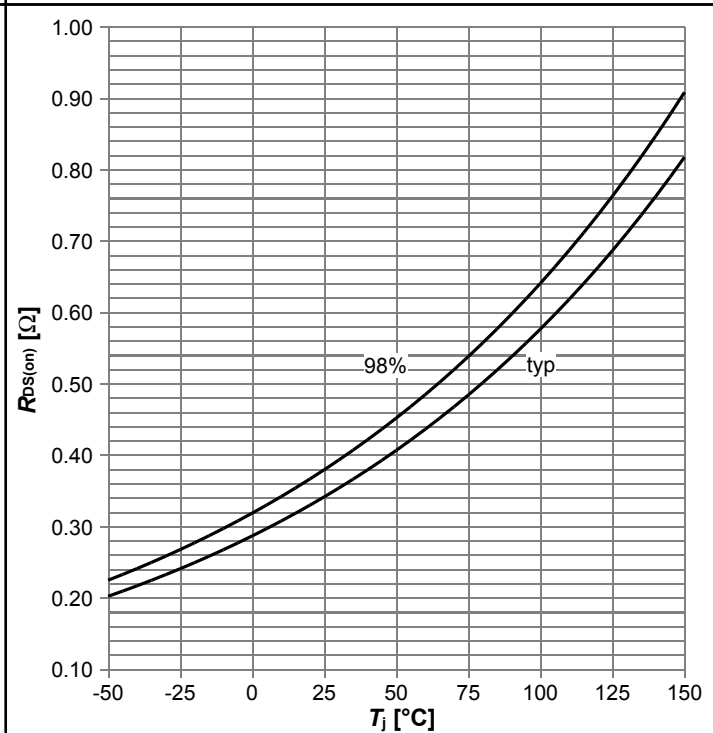
$I_D = f(V_{DS})$; $T_j = 125\text{ °C}$; parameter: V_{GS}

Diagram 11: Typ. drain-source on-state resistance



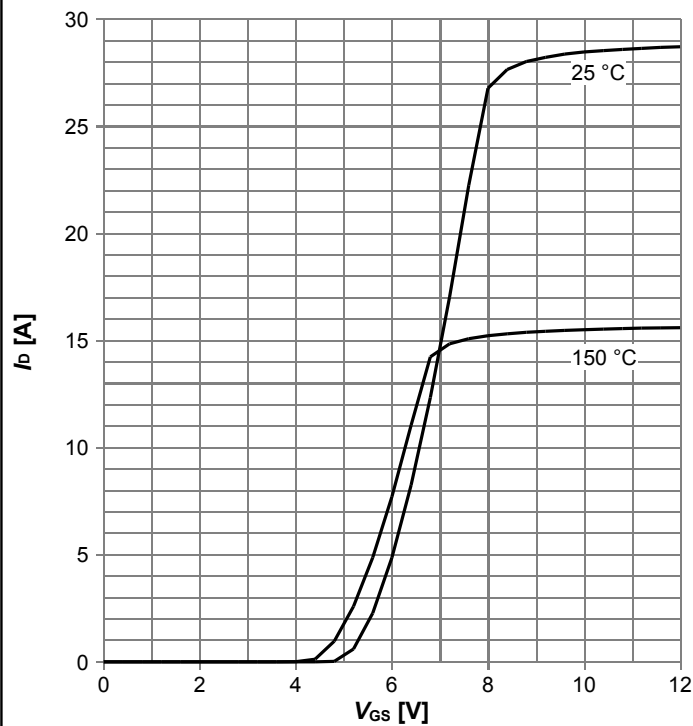
$R_{DS(on)} = f(I_D)$; $T_j = 125\text{ °C}$; parameter: V_{GS}

Diagram 12: Drain-source on-state resistance



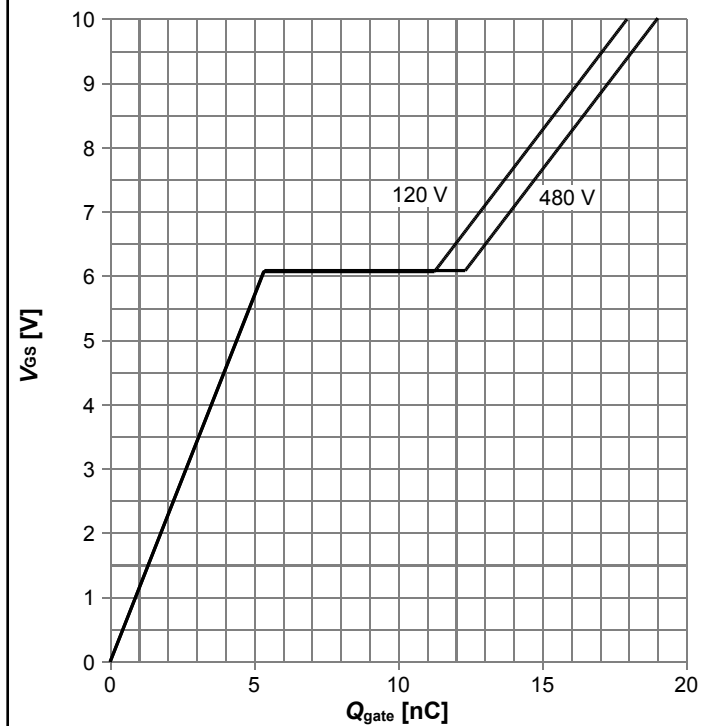
$R_{DS(on)} = f(T_j)$; $I_D = 3.8\text{ A}$; $V_{GS} = 10\text{ V}$

Diagram 13: Typ. transfer characteristics



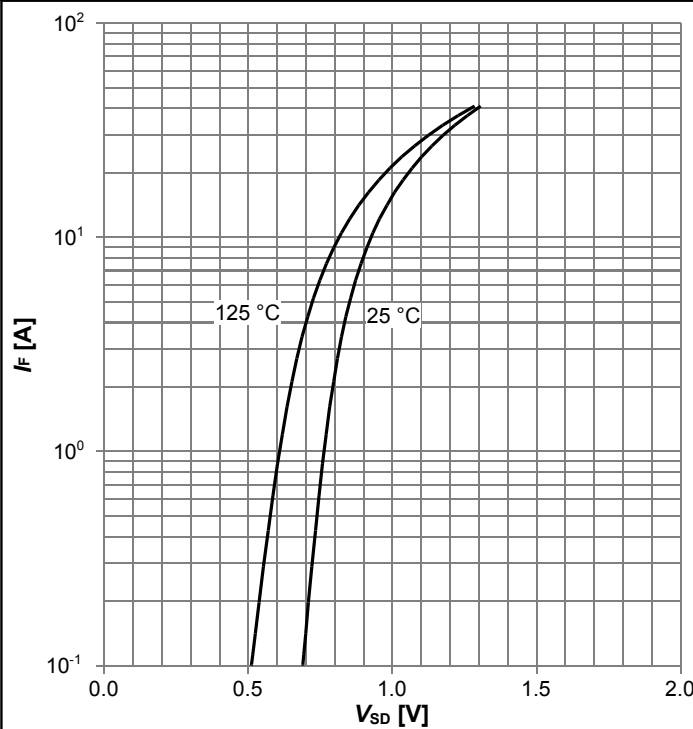
$I_D = f(V_{GS})$; $V_{DS} = 20$ V; parameter: T_j

Diagram 14: Typ. gate charge



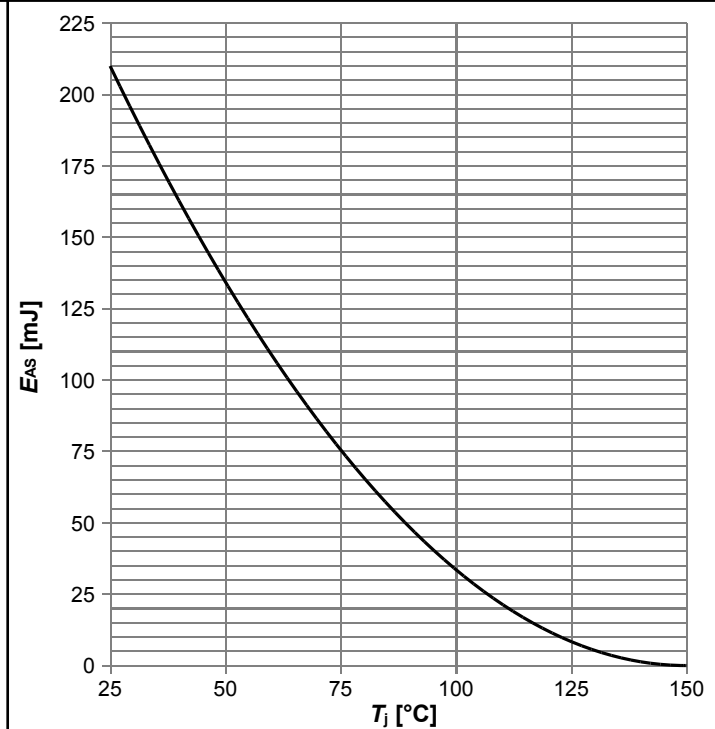
$V_{GS} = f(Q_{gate})$; $I_D = 4.8$ A pulsed; parameter: V_{DD}

Diagram 15: Forward characteristics of reverse diode



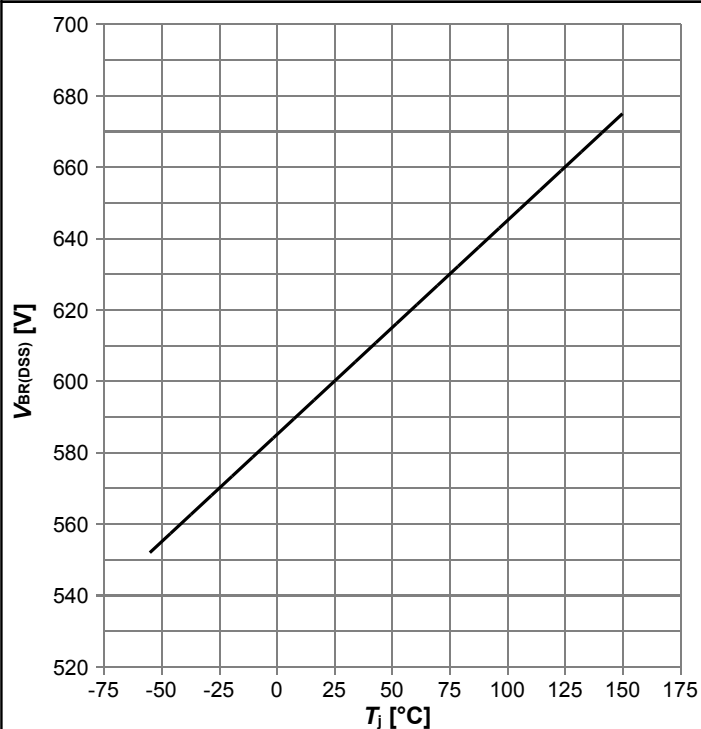
$I_F = f(V_{SD})$; parameter: T_j

Diagram 16: Avalanche energy



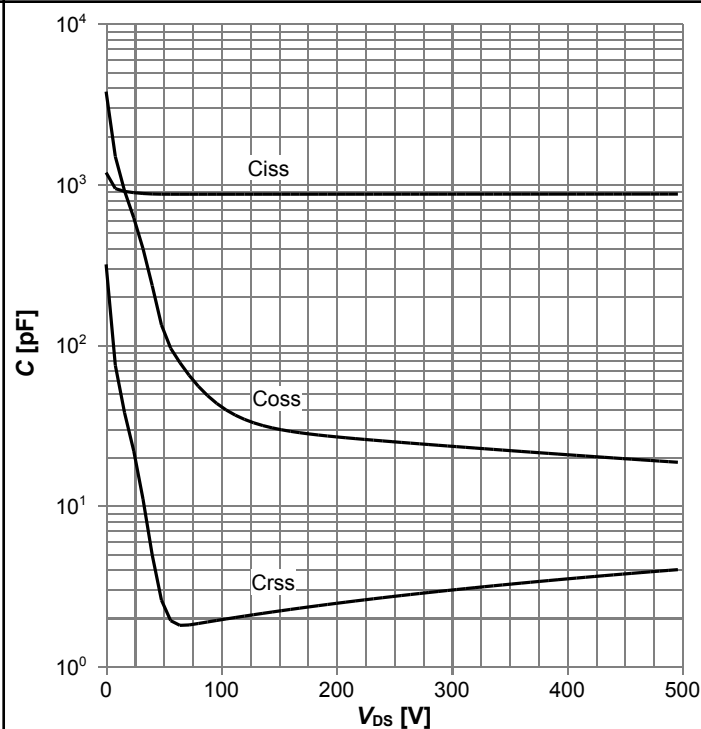
$E_{AS} = f(T_j)$; $I_D = 1.8$ A; $V_{DD} = 50$ V

Diagram 17: Drain-source breakdown voltage



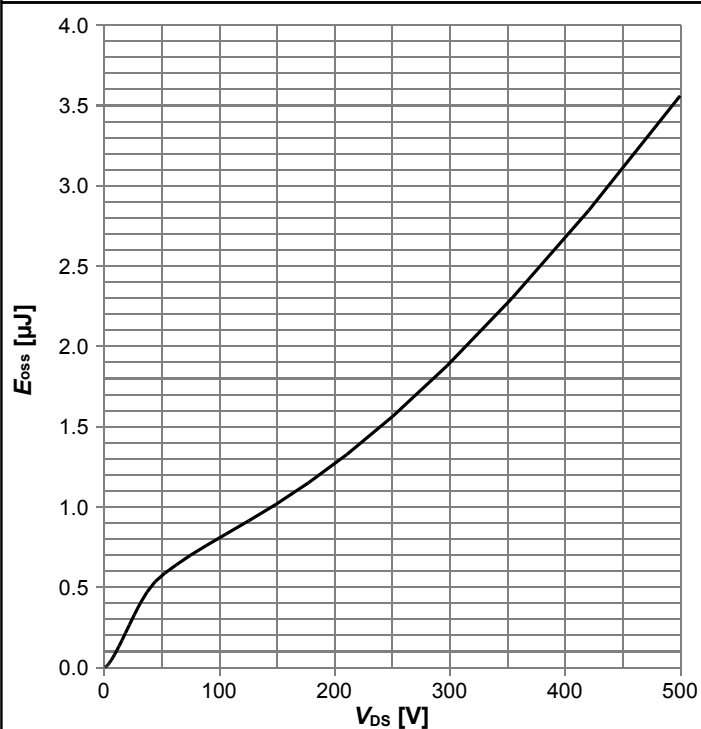
$V_{BR(DSS)} = f(T_j); I_D = 1 \text{ mA}$

Diagram 18: Typ. capacitances



$C = f(V_{DS}); V_{GS} = 0 \text{ V}; f = 1 \text{ MHz}$

Diagram 19: Typ. Coss stored energy



$E_{oss} = f(V_{DS})$

5 Test Circuits

Table 10 Diode characteristics

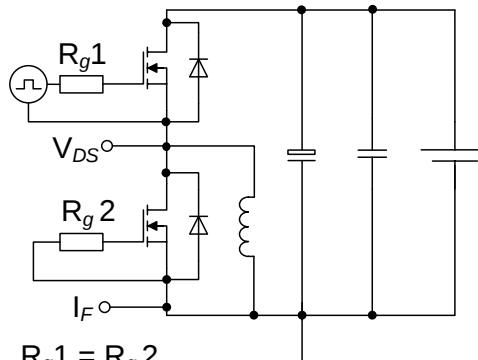
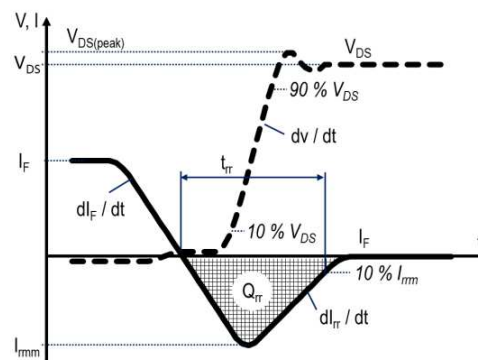
Test circuit for diode characteristics	Diode recovery waveform
 $R_{g1} = R_{g2}$	

Table 11 Switching times

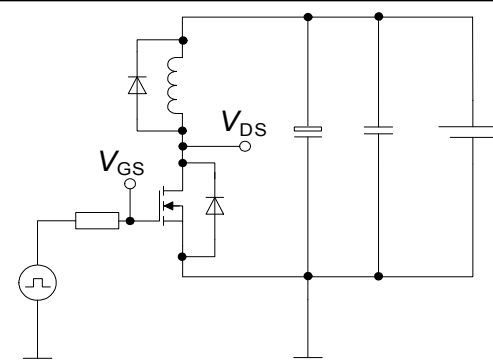
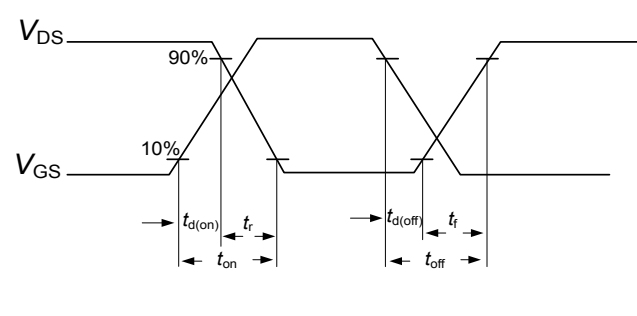
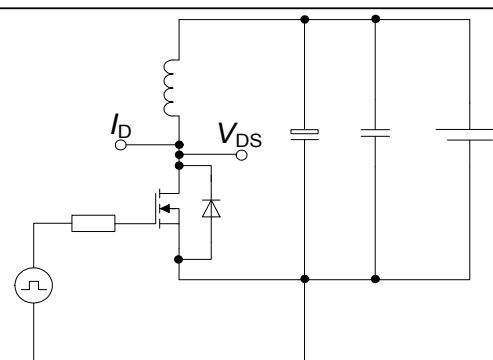
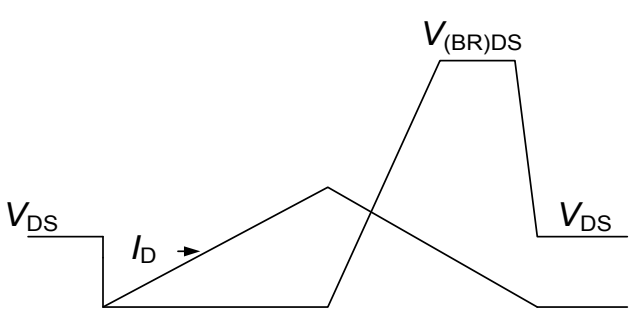
Switching times test circuit for inductive load	Switching times waveform
	

Table 12 Unclamped inductive load

Unclamped inductive load test circuit	Unclamped inductive waveform
	

6 Package Outlines

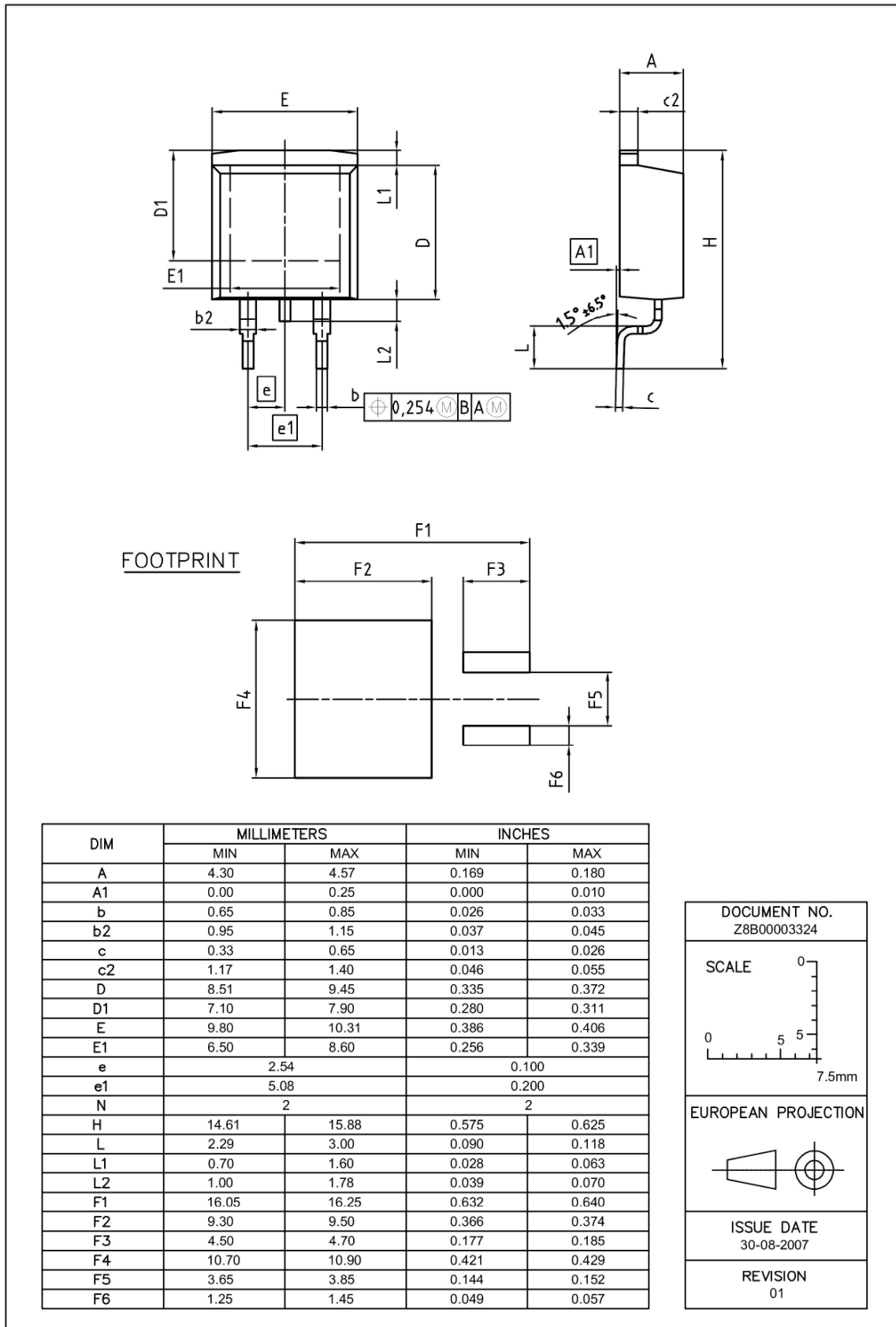


Figure 1 Outline PG-TO263-3, dimensions in mm/inches

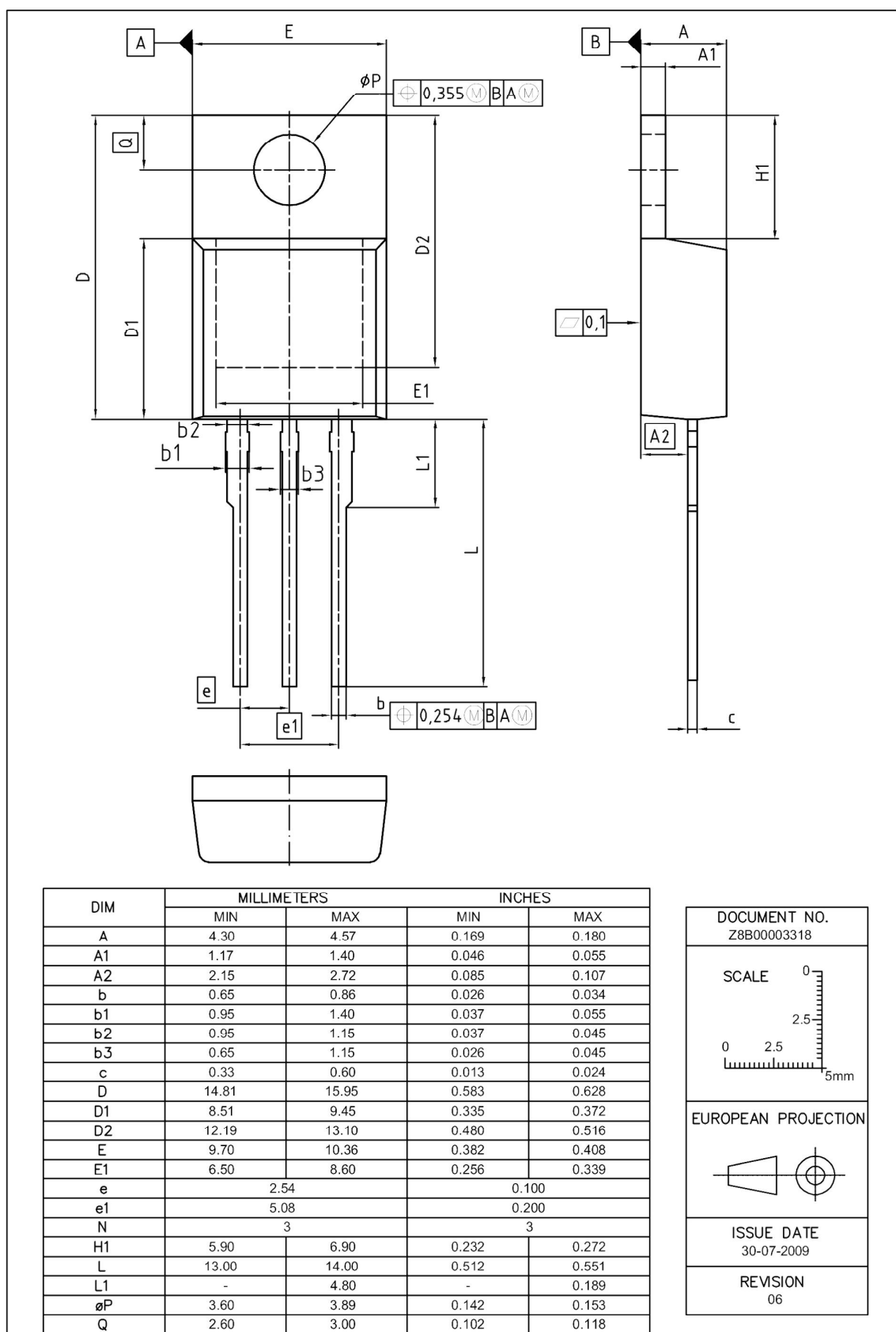
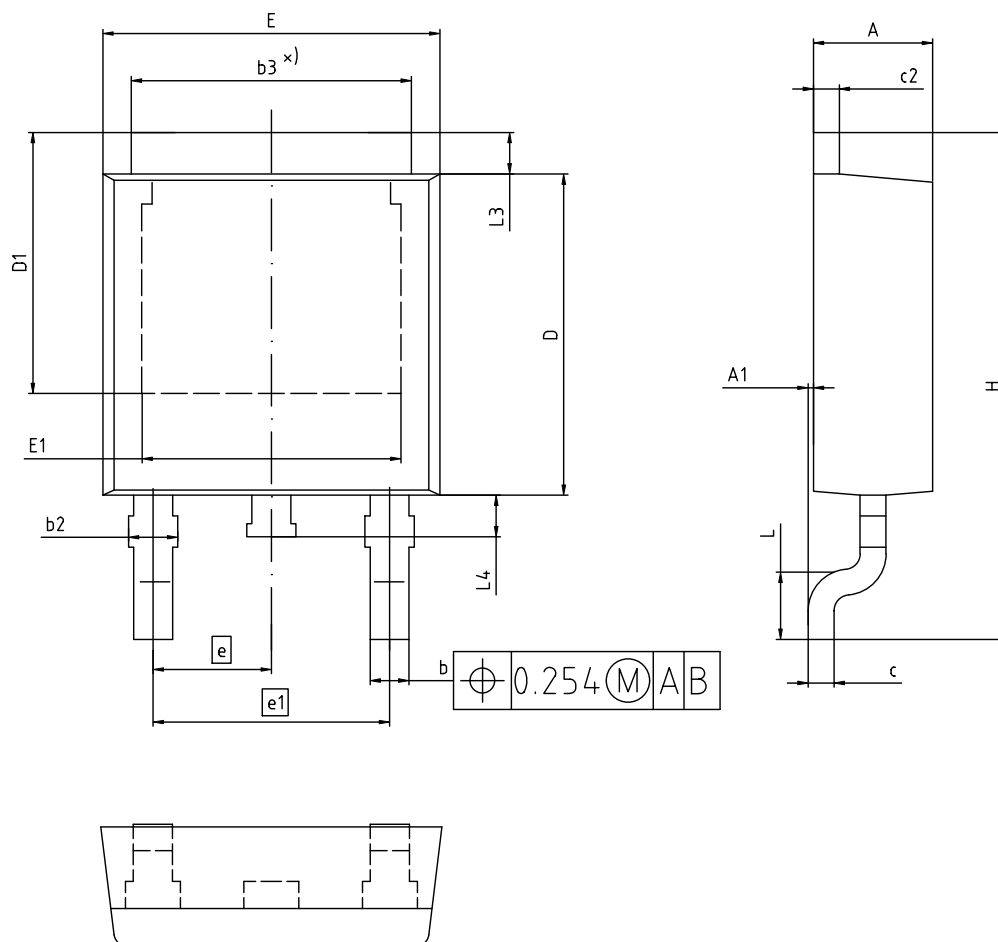


Figure 2 Outline PG-T0220-3, dimensions in mm/inches

PG-TO252-3 (DPAK)

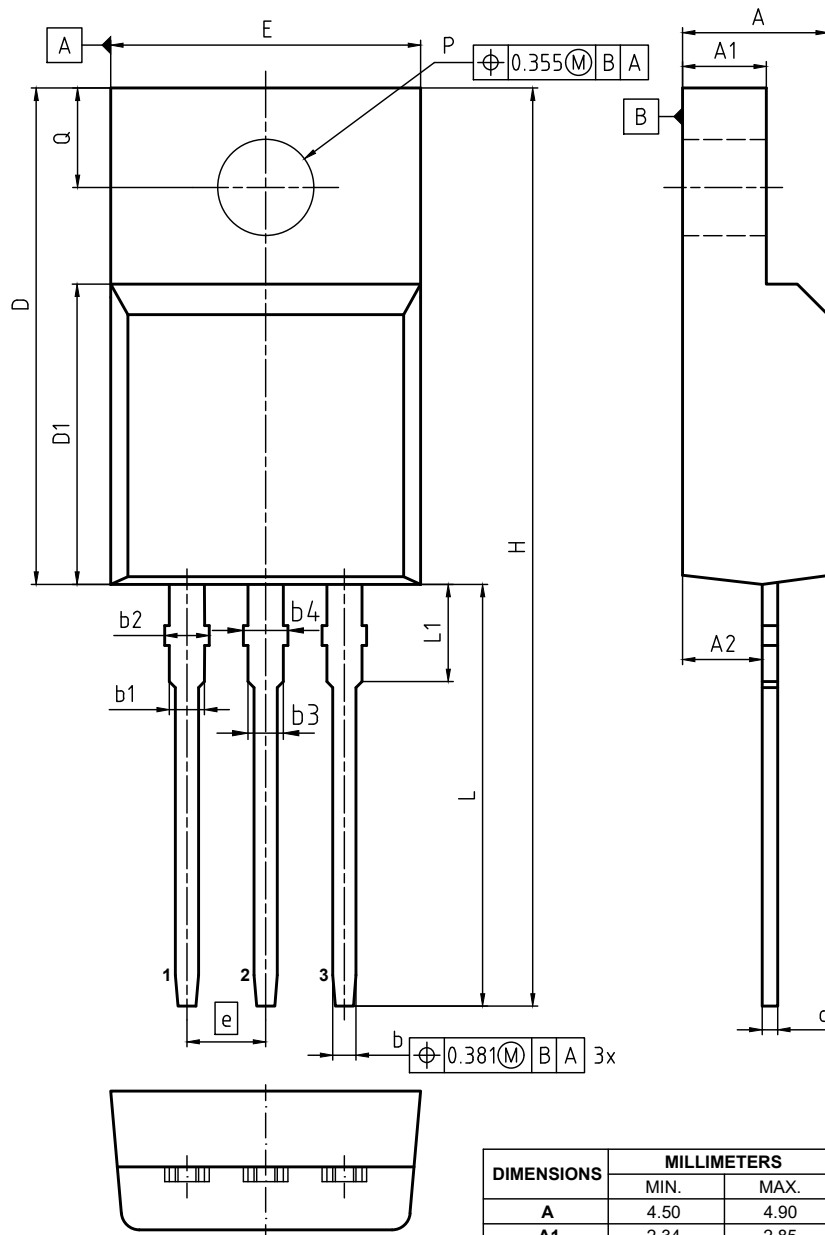


ALL DIMENSIONS REFER TO JEDEC
 STANDARD TO-252 AND DO NOT INCLUDE MOLD
 FLASH OR PROTRUSIONS.

DIMENSION	MILLIMETERS	
	MIN.	MAX.
A	2.16	2.41
A1	0.00	0.15
b	0.64	0.89
b2	0.65	1.15
b3	4.95	5.50
c	0.46	0.61
c2	0.40	0.98
D	5.97	6.22
D1	5.02	5.84
E	6.35	6.73
E1	4.32	5.50
e	2.29	
e1	4.57	
N	3	
H	9.40	10.48
L	1.18	1.78
L3	0.89	1.27
L4	0.51	1.02

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Figure 3 Outline PG-TO252-3, dimensions in mm/inches



NOTES:
 DIMENSIONS DO NOT INCLUDE MOLD FLASH, PRO-
 TRUSIONS OR GATE BURRS
 GATE BURRS ARE LESS THAN 0.5 mm

DIMENSIONS	MILLIMETERS	
	MIN.	MAX.
A	4.50	4.90
A1	2.34	2.85
A2	2.42	2.86
b	0.65	0.90
b1	0.95	1.38
b2	0.95	1.51
b3	0.65	1.38
b4	0.65	1.51
c	0.40	0.63
D	15.67	16.15
D1	8.97	9.83
E	10.00	10.65
e	2.54	
H	28.70	29.75
L	12.78	13.75
L1	2.83	3.45
øP	3.00	3.30
Q	3.15	3.50

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ISSUE DATE 21.03.2019
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Figure 4 Outline PG-T0220 FullPAK, dimensions in mm

7 Appendix A

Table 13 Related Links

- IFX CoolMOS™ P6 Webpage: www.infineon.com
- IFX CoolMOS™ P6 application note: www.infineon.com
- IFX CoolMOS™ P6 simulation model: www.infineon.com
- IFX Design tools: www.infineon.com

Revision History

IPB60R380P6, IPP60R380P6, IPD60R380P6, IPA60R380P6

Revision: 2020-06-09, Rev. 2.4

Previous Revision

Revision	Date	Subjects (major changes since last revision)
2.0	2013-12-05	Release of final version
2.1	2013-12-05	Release of multi-package datasheet
2.2	2015-07-10	PG-TO 263 package added
2.3	2017-08-22	Updated TO220 Full PAK package drawing on page 16
2.4	2020-06-09	Update DPAK, FullPAK package drawing, symbol drawing

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